What Is Claimed Is:

1. A multilayer printed board to be provided with electronic components, which has at least one layer whose thermal expansion behavior corresponds approximately to the thermal expansion behavior of said electronic components while at the same time substantially determining the thermal expansion behavior of said multilayer printed board.

2. The multilayer printed board according to claim 1, wherein said layer is a glass layer or a layer having a glass content, which is intimately bonded to other layer materials.

3. The multilayer printed board according to claim 1, wherein said layer is a thin glass film.

4. The multilayer printed board according to claim 1, wherein said layer has a thickness of between 30 and 1100μm.

5. The multilayer printed board according to claim 4, wherein said layer is between 50 and 500μm thick.

6. A multilayer printed board according to claim 2, wherein said glass layer is a borosilicate glass layer.

7. The multilayer printed board according to claim 2, wherein said other layer materials are thermoplastic or duroplastic materials, metals or electrically conducting or electrically nonconducting plastics.

8. The multilayer printed board according to claim 1, wherein said layer is disposed inside or as external layer of said multilayer printed board.

9. The multilayer printed board according to claim 1, wherein said intimate bonding of the single layers of which said multilayer printed board is composed occurs by means of pressing to a molded laminated material.

10. The multilayer printed board according to claim 1, wherein said layer can be utilized as a reinforcement material for laminates and prepregs and/or as an external layer in combination with thermoplastic or duroplastic polymers.

11. The multilayer printed board according to claim 1, wherein said layer is perforable, porous, structurable for optical applications, printable, physically coatable, chemically coatable, roll-to-roll processable and/or thermally moldable.